



Inventor: Kennedy et al.  
Serial No.: 09/547,167  
Attorney Dkt. No. 595.052-US1

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Art Unit: 2822  
Examiner: C. Novacek

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T. BELL  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231

Inventor: **Kennedy et al.**

Serial No: **09/547,167**

Filed: **April 11, 2000**

For: **The Use of Sacrificial  
Inorganic Dielectrics for  
Dual Damascene Processes  
Utilizing Organic Intermetal  
Dielectrics**

Examiner: C. Novacek

Art Unit: 2822

Attorney Docket No.: 595.052-US1

**RESPONSE TO OFFICE ACTION**

The Honorable Commissioner  
of Patents and Trademarks  
Washington, D.C. 20231

Dear Sir:

This paper responds to the Office Action dated August 24, 2001. The three-month deadline, November 24<sup>th</sup>, falls on a Saturday; and therefore, this response is timely filed on Monday, November 26<sup>th</sup>, which is the next business day. Please enter the following:

**IN THE CLAIMS (Clean Copy of Claims – Marked Up Copy Attached)**

1. (Amended) A method of making conducting vias and conducting lines on a substrate comprising:
- depositing a stack having a top surface on a substrate, wherein the stack comprises a first organic intermetal dielectric layer and a hardmask layer;